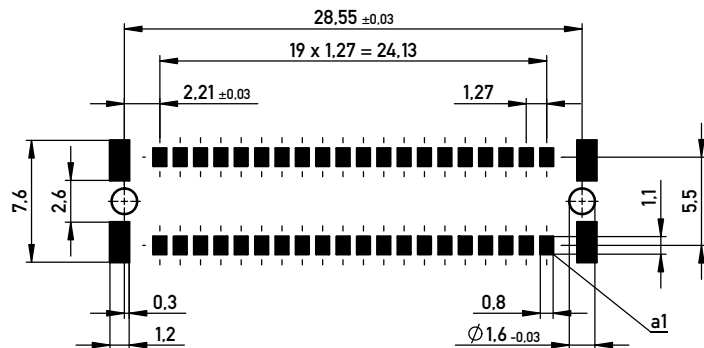


Leiterplatten-Layout Vorschlag für SMT  
PCB-Layout Proposal for SMT



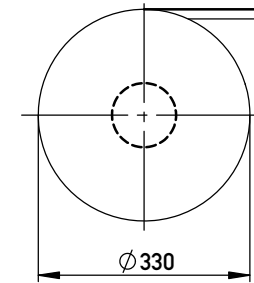
Verpackt im Gurt nach DIN IEC 60286-3  
Tape on Reel Packaging according to DIN IEC 60286-3  
Verpackungseinheit: 280 Stück  
Packaging unit: 280 pcs

Anforderungsstufe 1  
Performance Level 1

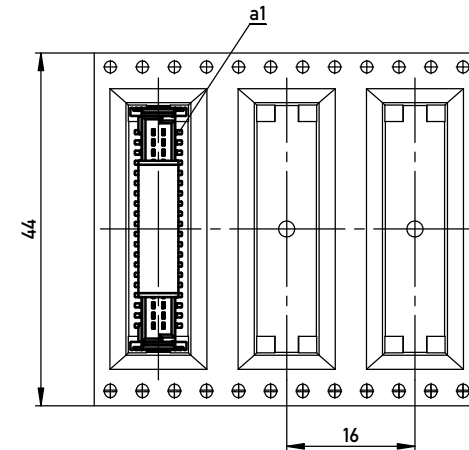
Kontaktbereich vergoldet  
Mating Area gold plating

Anschlussbereich verzinkt 4-6 µm  
Terminal Area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0,1 mm  
Coplanarity Area of Termination ≤ 0,1 mm



Abspulrichtung - Reel off Direction



BA 8-13 - 8mm Bauhöhe  
type 8-13 - Low Profile

Information:		Tolerances	All Dimensions in mm	Scale 3:1
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e		www.ERNI.com		254590
Index		14.07.2015		I
		Date		A3
Class				SMCQ

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